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- Contains Eight Flip-Flops With Single-Rail Outputs
- Buffered Clock and Direct Clear Inputs
- Individual Data Input to Each Flip-Flop
- Applications Include: Buffer/Storage Registers Shift Registers Pattern Generators

description

These monolithic, positive-edge-triggered flipflops utilize TTL circuitry to implement D-type flip-flop logic with a direct clear input.

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect ar the output.

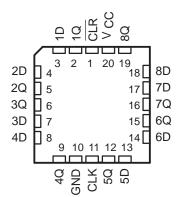
These flip-flops are guaranteed to respond to clock frequencies ranging form 0 to 30 megahertz while maximum clock frequency is typically 40 megahertz. Typical power dissipation is 39 milliwatts per flip-flop for the '273 and 10 milliwatts for the 'LS273.

FUNCTION TABLE (each flip-flop)

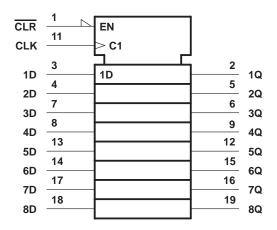
(eden inp inep)											
	NPUTS		OUTPUT								
CLEAR	CLOCK	D	Q								
L	Х	Х	L								
н	\uparrow	Н	н								
н	\uparrow	L	L								
н	L	Х	Q ₀								

CLR [1	U	20] v _{cc}
1Q [2		19] 8Q
1D [3		18] 8D
2D [4		17]7D
2Q [5		16] 7Q
3Q [6		15] 6Q
3D [7		14] 6D
4D [8		13] 5D
4Q [9		12] 5Q
GND [10		11] CLK

SN54LS273 . . . FK PACKAGE (TOP VIEW)



logic symbol[†]

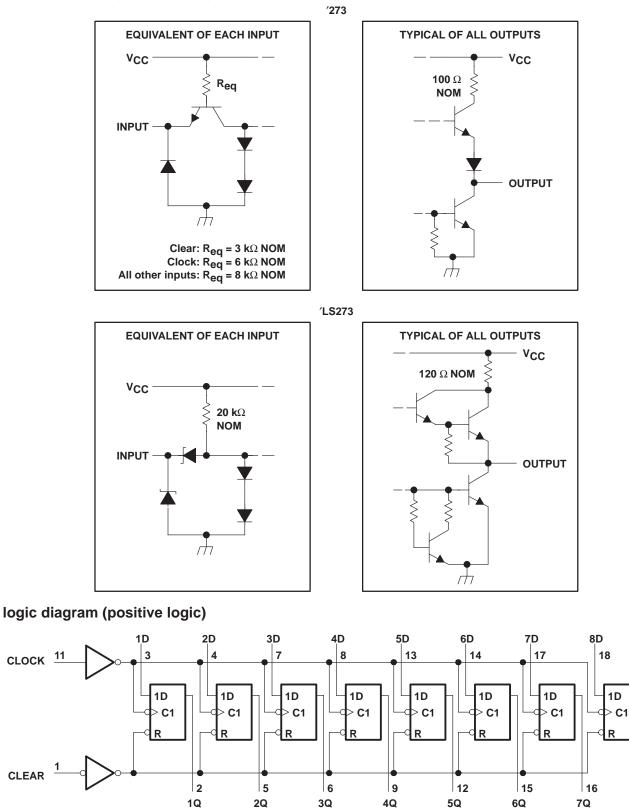


[†] This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, J, N, and W packages.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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schematics of inputs and outputs



Pin numbers shown are for the DW, J, N, and W packages.



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8Q

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	
Input voltage	5.5 V
Operating free-air temperature range, T _A : SN54273	5°C to 125°C
SN74273	0°C to 70°C
Storage temperature range	5°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN54273	;	5	SN74273		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH				-800			-800	μA
Low-level output current, IOL				16			16	mA
Clock frequency, f _{clock}		0		30	0		30	MHz
Width of clock or clear pulse, t _W		16.5			16.5			ns
Cotup time t	Data input	20↑			20↑			
Setup time, t _{su}	Clear inactive state	25↑			25↑			ns
Data hold time, t _h		5↑			5↑			ns
Operating free-air temperature, TA		-55		125	0		70	°C

 \uparrow The arrow indicates that the rising edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST C	ONDITIONS [†]	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage				2			V
VIL	Low-level input voltage						0.8	V
VIK	Input clamp voltage		$V_{CC} = MIN,$	lj = -12 mA			-1.5	V
∨он	High-level output voltage	$V_{CC} = MIN,$ $V_{IL} = 0.8 V,$	V _{IH} = 2 V, I _{OH} = −800 μA	2.4	3.4		V	
V _{OL}	Low-level output voltage		V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OH} = 16 mA			0.4	V
Ιį	Input current at maximum input voltag	е	V _{CC} = MAX,	V _I = 5.5 V			1	mA
1	High lovel input ourrept	Clear		V ₁ = 2.4 V			80	
ЧН	High-level input current	Clock or D	$V_{CC} = MAX,$	v = 2.4 v			40	μA
1	Low-level input current	Clear	VCC = MAX,	$V_{I} = 0.4 V$			-3.2	mA
۱L	Low-level input current	Clock or D	VCC = WAX,	v] = 0.4 v			-1.6	ША
IOS	Short-circuit output current§		$V_{CC} = MAX$		-18		-57	mA
ICC	Supply current		V _{CC} = MAX,	See Note 2		62	94	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25° C.

§ Not more than one output should be shorted at a time.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.



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switching characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency		30	40		MHz
^t PHL	Propagation delay time, high-to-low-level output from clear	CL = 15 pF,		18	27	ns
^t PLH	Propagation delay time, low-to-high-level output from clock	R _L = 400 Ω, See Note 3		17	27	ns
^t PHL	Propagation delay time, high-to-low-level output from clock			18	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	
Operating free-air temperature range, T _A : SN54LS273 SN74LS273	-55°C to 125°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SI	N54LS27	73	SN74LS273			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
	4.5	5	5.5	4.75	5	5.25	V
			-400			-400	μΑ
Low-level output current, IOL						8	mA
Clock frequency, f _{clock}				0		30	MHz
	20			20			ns
Data input	20↑			20↑			
Clear inactive state	25↑			25↑			ns
	5↑			5↑			ns
	-55		125	0		70	°C
		MIN 4.5 0 20 Data input 20↑ Clear inactive state 25↑ 5↑	MIN NOM 4.5 5 0 20 Data input 20^1 Clear inactive state 25^1 51	4.5 5 5.5 -400 -400 4 0 30 20 20 Data input 20↑ Clear inactive state 25↑ 5↑ 5↑	MIN NOM MAX MIN 4.5 5 5.5 4.75 4.5 5 5.5 4.75 -400 -400 -400 0 -400 -400 0 30 0 20 20 20 Data input 20^1 20^1 Clear inactive state 25 [↑] 25 [↑]	MIN NOM MAX MIN NOM 4.5 5 5.5 4.75 5 -400 -400 -400 -400 -400	MIN NOM MAX MIN NOM MAX 4.5 5 5.5 4.75 5.5 5.25 -400 -400 -400 -400 -400 400 400 400 -400 -400 400 400 400 400 -400

 \uparrow The arrow indicates that the rising edge of the clock pulse is used for reference.



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DADAMETED		TEST CONDITIONS ^T			S	N54LS27	'3	SI	N74LS27	3	
	PARAMETER	IES	I CONDITION	151	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	lı = – 18 mA				-1.5			-1.5	V
VOH	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, I _{OH} = -400	μΑ	2.5	3.4		2.7	3.4		V
Vai		V _{CC} = MIN,	VIH = 2 V,	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
VOL	Low-level output voltage	$V_{IL} = V_{IL}max$,		$I_{OL} = 8 \text{ mA}$					0.35	0.5	v
II.	Input current at maximum input voltage	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
Ι _{ΙΗ}	High-level input current	V _{CC} = MAX,	V _I = 2.7 V				20			20	μΑ
١ _{IL}	Low-level input current	V _{CC} = MAX,	V _I = 0.4 V				-0.4			-0.4	mA
IOS	Short-circuit output current§	V _{CC} = MAX			-20		-100	-20		-100	mA
ICC	Supply current	V _{CC} = MAX,	See Note 2			17	27		17	27	mA

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

§ Not more than one output should be shorted at a time and duration of short circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.

switching characteristics, V_{CC} = 5 V, T_A = 25° C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency		30	40		MHz
^t PHL	Propagation delay time, high-to-low-level output from clear	C _L = 15 pF, R _I = 2 kΩ,		18	27	ns
^t PLH	Propagation delay time, low-to-high-level output from clock	$R_L = 2 R_{32}$, See Note 3		17	27	ns
^t PHL	Propagation delay time, high-to-low-level output from clock			18	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



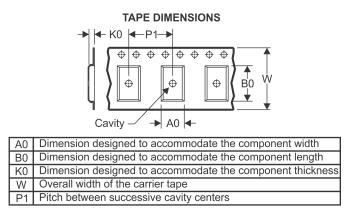
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS273DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS273NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

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PACKAGE MATERIALS INFORMATION

6-May-2017



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS273DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS273NSR	SO	NS	20	2000	367.0	367.0	45.0

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